




PCN Number:	20210127000.1	PCN Date:	Feb. 3, 2021												
Title:	Qualification of SCK as an additional Assembly site for Select Devices														
Customer Contact:	PCN Manager	Dept:	Quality Services												
Proposed 1st Ship Date:	May 3, 2021	Estimated Sample Availability:	Date provided at sample request												
Change Type:															
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design												
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet												
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change												
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site												
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process												
		<input type="checkbox"/>	Wafer Bump Site												
		<input type="checkbox"/>	Wafer Bump Material												
		<input type="checkbox"/>	Wafer Bump Process												
		<input type="checkbox"/>	Wafer Fab Site												
		<input type="checkbox"/>	Wafer Fab Materials												
		<input type="checkbox"/>	Wafer Fab Process												
PCN Details															
Description of Change:															
Texas Instruments is pleased to announce the qualification of SCK (STATS ChipPac Korea) as an additional assembly site for the list of devices below. No material differences between assembly sites.															
Reason for Change:															
Continuity of Supply															
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):															
None															
Anticipated impact on Material Declaration															
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp												
Changes to product identification resulting from this PCN:															
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>Assembly Country Code (23L)</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>AMKOR K4</td> <td>AK4</td> <td>KOR</td> <td>Gwangju</td> </tr> <tr> <td>STATS ChipPac</td> <td>SCK</td> <td>KOR</td> <td>Incheon</td> </tr> </tbody> </table>				Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	AMKOR K4	AK4	KOR	Gwangju	STATS ChipPac	SCK	KOR	Incheon
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City												
AMKOR K4	AK4	KOR	Gwangju												
STATS ChipPac	SCK	KOR	Incheon												
Sample product shipping label (not actual product label)															
   <p> (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS </p> <p> MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750 </p>															
Product Affected:															
AFE7700IABJ	AFE7799IABJ	SN1805358IABJ													
AFE7769IABJ	SN1710796IABJ														

Qualification Report

Approve Date 23-Jul-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN1710796ABJ	QBS Product Reference: AFE7798
ED	Electrical Characterization.	Full Temperature & Voltage range	3/30/0	3/30/0
CDM	ESD - CDM	150 V	3/9/0	1/3/0
LU	Latch-up	(per JESD78)	-	3/18/0
HTOL	HTOL	1000	-	3/234/0
TC	Temperature Cycle, -55/125C	700	3/231/0	3/299/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000	3/231/0	3/230/0
UHAST	Unbiased HAST 110C/85%RH	264	3/231/0	1/80/0
HTSL	High Temp Storage Bake 150C	1000	3/231/0	3/240/0
SD	Pb Surface Mount Solderability	Pb/Solder	3/66/0	1/22/0
FLAM	Flammability (UL 94V-0)	Method A/UL 94V-0	2/10/0	1/5/0
MISC	Salt Atmosphere	Salt/Atmos	3/66/0	-
PD	Physical Dimensions	(per mechanical drawing)	1/5/0	3/15/0
SBS	Solder Ball Shear	-	3/15/0	1/4/0
SD	Pb Free Surface Mount Solderability	Pb Free/Solder	3/66/0	1/22/0

- QBS: Qual By Similarity

- Qual Device SN1710796ABJ is qualified at LEVEL3-260C

- **Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable**

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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